

SNx4HC240 Octal Buffers and Line Drivers With 3-State Outputs

1 Features

- Wide operating voltage range of 2V to 6V
- High-current outputs drive up to 15 LSTTL loads
- Low power consumption, 80 μ A max I_{CC}
- Typical $t_{pd} = 9\text{ns}$
- $\pm 6\text{mA}$ output drive at 5V
- Low input current of 1 μ A max
- 3-state outputs drive bus lines or buffer memory address registers

2 Description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The 'HC240 devices are organized as two 4-bit buffers/drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes inverted data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

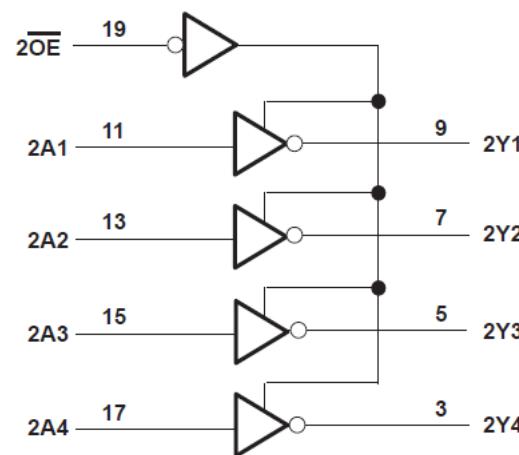
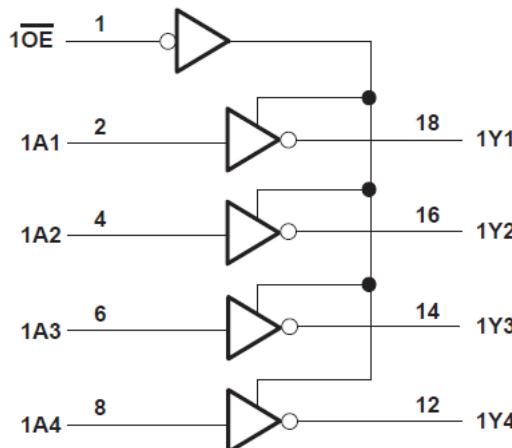
Device Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾	BODY SIZE ⁽³⁾
SN74HC240	DW (SOIC, 20)	12.80mm x 10.3mm	12.80mm x 7.50mm
	DB (SSOP, 20)	7.2mm x 7.8mm	7.2mm x 5.30mm
	DGS (VSSOP, 20)	5.1mm x 4.9mm	5.1mm x 3mm
	PDIP (20)	24.33mm x 9.4mm	24.33mm x 6.35mm
	NS (SOP, 20)	12.6mm x 7.8mm	12.6mm x 5.3mm
	PW (TSSOP, 20)	6.50mm x 6.4mm	6.50mm x 4.40mm
SNx4HC240	J (CDIP, 20)	24.2mm x 7.62mm	24.2 mm x 6.92mm
	FK (LCCC, 20)	8.9mm x 8.9mm	8.9mm x 8.9mm
	W (CFP, 20)	13.09mm x 8.13mm	13.09mm x 6.92mm

(1) For more information, see [Mechanical, Packaging, and Orderable Information](#).

(2) The package size (length x width) is a nominal value and includes pins, where applicable.

(3) The body size (length x width) is a nominal value and does not include pins.



Functional Block Diagram

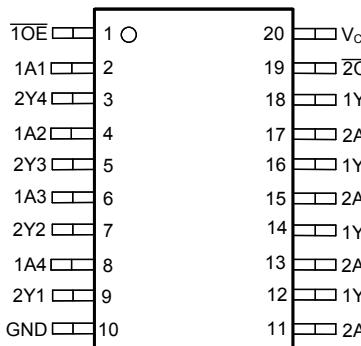


An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

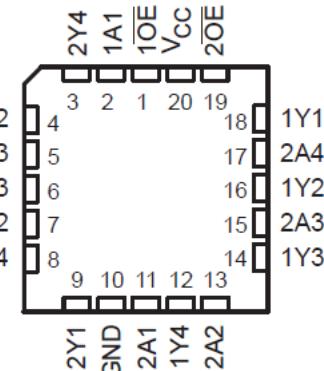
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3 Pin Configuration and Functions



J, W, DB, DGS, DW, N, NS, or PW package
20-Pin CDIP, CFP, SSOP, SOIC, PDIP, SO, TSSOP
(Top View)



FK package
20-Pin LCCC
(Top View)

Table 3-1. Pin Functions

NAME	PIN	TYPE	DESCRIPTION
1OE	1	I	Output enable 1
1A1	2	I	1A1 input
2Y4	3	O	2Y4 output
1A2	4	I	1A2 input
2Y3	5	O	2Y3 output
1A3	6	I	1A3 input
2Y2	7	O	2Y2 output
1A4	8	I	1A4 input
2Y1	9	O	2Y1 output
GND	10	—	Ground pin
2A1	11	I	2A1 input
1Y4	12	O	1Y4 output
2A2	13	I	2A2 input
1Y3	14	O	1Y3 output
2A3	15	I	2A3 input
1Y2	16	O	1Y2 output
2A4	17	I	2A4 input
1Y1	18	O	1Y1 output
2OE	19	I	Output enable 2
VCC	20	—	Power pin

1. I = input, O = output, P = power, FB = feedback, GND = ground, N/A = not applicable

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	7	V
I _{IK}	Input clamp current ⁽²⁾	V _I < 0 or V _I > V _{CC}		±20	mA
I _{OK}	Output clamp current ⁽²⁾	V _O < 0 or V _O > V _{CC}		±20	mA
I _O	Continuous output current	V _O = 0 to V _{CC}		±35	mA
	Continuous current through V _{CC} or GND			±70	mA
T _J	Junction temperature			150	°C
T _{stg}	Storage temperature range		-65	150	°C
	Lead temperature (Soldering 10s) (SOIC - Lead Tips Only)			300	°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

4.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN54HC240			SN74HC240			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5			V
		V _{CC} = 4.5 V	3.15		3.15			
		V _{CC} = 6 V	4.2		4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.5		0.5		V
		V _{CC} = 4.5 V		1.35		1.35		
		V _{CC} = 6 V		1.8		1.8		
V _I	Input voltage	0	V _{CC}		0	V _{CC}		V
V _O	Output voltage	0	V _{CC}		0	V _{CC}		V
Δt/Δv	Input transition rise and fall time	V _{CC} = 2 V		1000		1000		ns
		V _{CC} = 4.5 V		500		500		
		V _{CC} = 6 V		400		400		
T _A	Operating free-air temperature	-55		125	-40		85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

4.3 Thermal Information

THERMAL METRIC	SN74HC240						UNIT	
	DW (SOIC)	DB (SSOP)	DGS (VSSOP)	N (PDIP)	NS (SOP)	PW (TSSOP)		
	20 PINS	20 PINS	20 PINS	20 PINS	20 PINS	20 PINS		
R _{θJA}	Junction-to-ambient thermal resistance ⁽¹⁾	109.1	122.7	130.6	84.6	113.4	131.8	°C/W
R _{θJC} (top)	Junction-to-case (top) thermal resistance	76	81.6	68.7	72.5	78.6	72.2	°C/W
R _{θJB}	Junction-to-board thermal resistance	77.6	77.5	85.4	65.3	78.4	82.8	°C/W

4.3 Thermal Information (continued)

THERMAL METRIC		SN74HC240						UNIT
		DW (SOIC)	DB (SSOP)	DGS (VSSOP)	N (PDIP)	NS (SOP)	PW (TSSOP)	
		20 PINS	20 PINS	20 PINS	20 PINS	20 PINS	20 PINS	
Ψ_{JT}	Junction-to-top characterization parameter	51.5	46.1	10.5	55.3	47.1	21.5	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	77.1	77.1	85.0	65.2	78.1	82.4	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54HC240		SN74HC240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998	1.9		1.9		V
			4.5 V	4.4	4.499	4.4		4.4		
			6 V	5.9	5.999	5.9		5.9		
		I _{OH} = -6 mA	4.5 V	3.98	4.3	3.7		3.84		
		I _{OH} = -7.8 mA	6 V	5.48	5.8	5.2		5.34		
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V	0.002	0.1	0.1		0.1		V
			4.5 V	0.001	0.1	0.1		0.1		
			6 V	0.001	0.1	0.1		0.1		
		I _{OL} = 6 mA	4.5 V	0.17	0.26	0.4		0.33		
		I _{OL} = 7.8 mA	6 V	0.15	0.26	0.4		0.33		
I _I	V _I = V _{CC} or 0	6 V	±0.1	±100	±1000	±1000		±1000	nA	
I _{OZ}	V _O = V _{CC} or 0	6 V	±0.01	±0.5	±10	±10		±5	μA	
I _{CC}	V _I = V _{CC} or 0, I _O = 0	6 V		8	160	160		80	μA	
C _i		2 V to 6 V	3	10	10	10		10	pF	

4.5 Switching Characteristics

over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see [Figure 5-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC240		SN74HC240		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	2 V	50	100	150	125				ns
			4.5 V	10	20	30	25				
			6 V	9	17	25	21				
t _{en}	OE	Y	2 V	75	150	225	190				ns
			4.5 V	15	30	45	38				
			6 V	13	26	38	32				
t _{dis}	OE	Y	2 V	44	150	225	190				ns
			4.5 V	22	30	45	38				
			6 V	21	26	38	32				

over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see [Figure 5-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC240		SN74HC240		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _t		Y	2 V		28	60		90		75	ns
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	

4.6 Switching Characteristics

over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see [Figure 5-1](#))

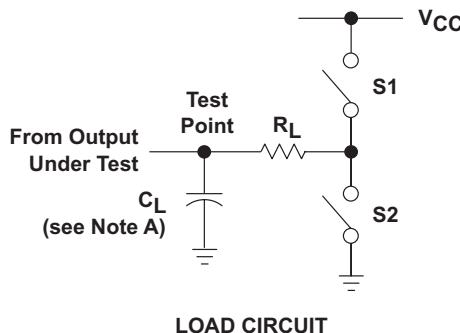
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{cc}	$T_A = 25^\circ\text{C}$			SN54HC240		SN74HC240		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	2 V	75	150	225	190				ns
			4.5 V	15	30	45	38				
			6 V	13	26	38	32				
t_{en}	\overline{OE}	Y	2 V	100	200	300	250				ns
			4.5 V	20	40	60	50				
			6 V	17	34	51	43				
t_t		Y	2 V	45	210	315	265				ns
			4.5 V	17	42	63	53				
			6 V	13	36	53	45				

4.7 Operating Characteristics

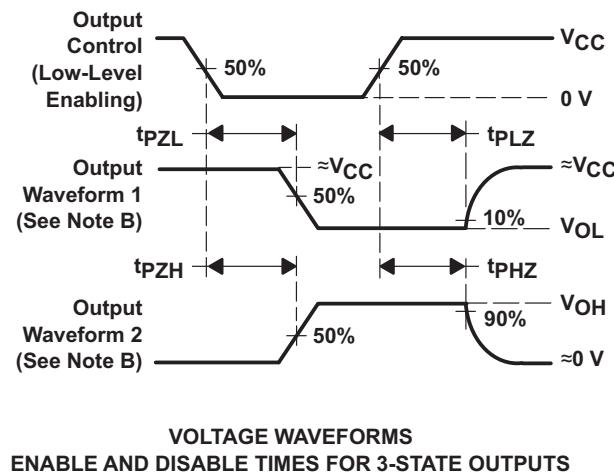
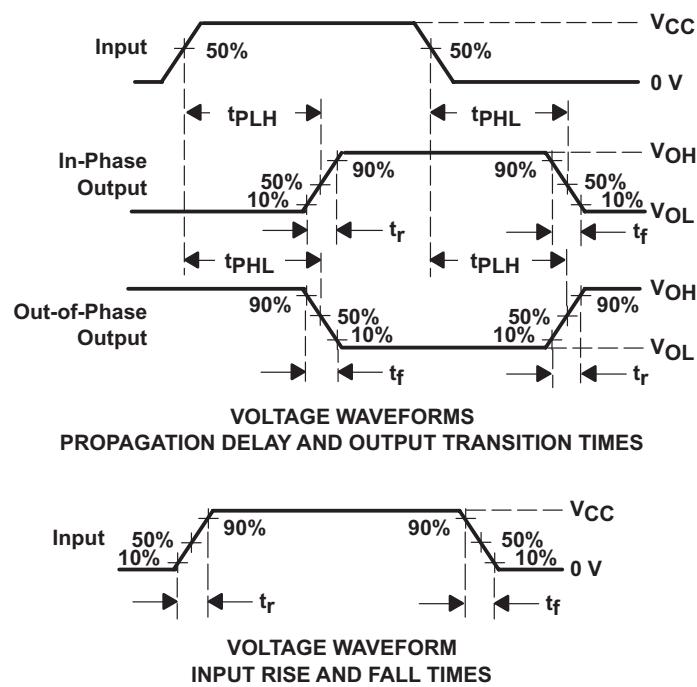
$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance per buffer/driver	No load	35	pF

5 Parameter Measurement Information



PARAMETER	R_L	C_L	S1	S2
t_{en}	1 k Ω	50 pF	Open	Closed
		or 150 pF	Closed	Open
t_{dis}	1 k Ω	50 pF	Open	Closed
		or 150 pF	Closed	Open
t_{pd} or t_t	--	50 pF or 150 pF	Open	Open



NOTES:

- C_L includes probe and test-fixture capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
- The outputs are measured one at a time with one input transition per measurement.
- t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- t_{PZL} and t_{PZH} are the same as t_{en} .
- t_{PLH} and t_{PHL} are the same as t_{pd} .

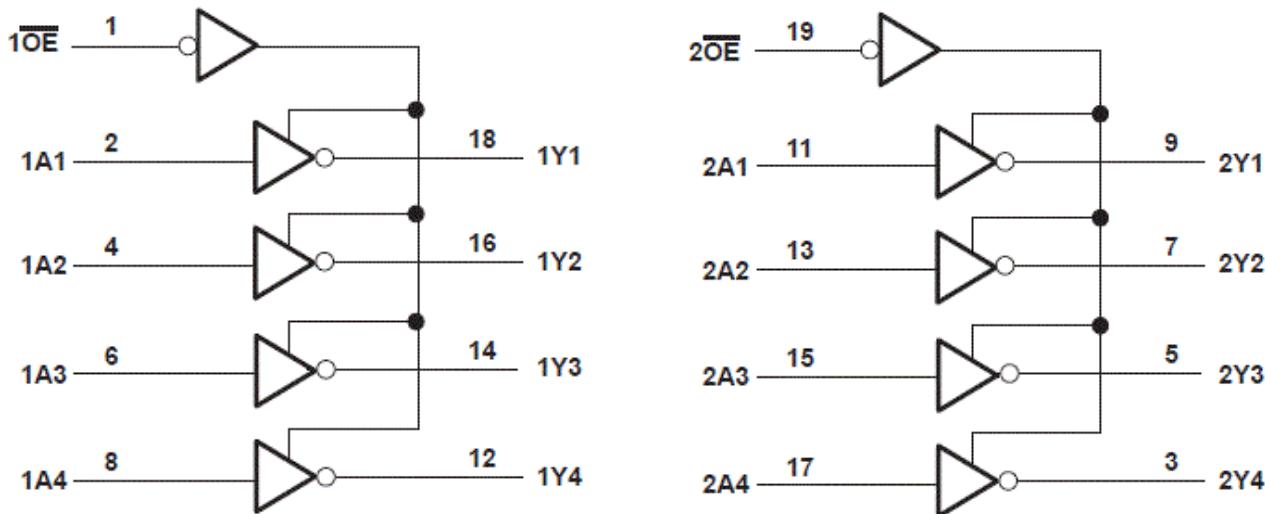
Figure 5-1. Load Circuit and Voltage Waveforms

6 Detailed Description

6.1 Overview

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The 'HC240 devices are organized as two 4-bit buffers/drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes inverted data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

6.2 Functional Block Diagram



6.3 Device Functional Modes

**Table 6-1. Function Table
(each buffer/driver)**

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	L
L	L	H
H	X	Z

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A $0.1\mu F$ capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The $0.1\mu F$ and $1\mu F$ capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

7.2 Layout

7.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices, inputs must never be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 Documentation Support

8.1.1 Related Documentation

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

8.4 Trademarks

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All trademarks are the property of their respective owners.

8.5 Electrostatic Discharge Caution

 This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision G (April 2022) to Revision H (August 2024)	Page
• Added DGS package to <i>Device Information</i> table, <i>Pin Configuration and Functions</i> section, and <i>Thermal Information</i> table.....	1
• Added package size to <i>Device Information</i> table.....	1
• Added <i>Pin Functions</i> table.....	3

Changes from Revision F (December 2021) to Revision G (April 2022)	Page
• Added <i>Application and Implementation</i> section.....	10

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
84074012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84074012A SNJ54HC 240FK
8407401RA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8407401RA SNJ54HC240J
8407401SA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8407401SA SNJ54HC240W
JM38510/65703B2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65703B2A
JM38510/65703B2A.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65703B2A
JM38510/65703BRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65703BRA
JM38510/65703BRA.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65703BRA
M38510/65703B2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65703B2A
M38510/65703BRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65703BRA
SN54HC240J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC240J
SN54HC240J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC240J
SN74HC240DBR	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC240
SN74HC240DBR.A	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC240
SN74HC240DGSR	Active	Production	VSSOP (DGS) 20	5000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC240
SN74HC240DGSR.A	Active	Production	VSSOP (DGS) 20	5000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC240
SN74HC240DW	Obsolete	Production	SOIC (DW) 20	-	-	Call TI	Call TI	-40 to 85	HC240
SN74HC240DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC240
SN74HC240DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC240
SN74HC240N	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC240N
SN74HC240N.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC240N
SN74HC240NE4	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC240N
SN74HC240NSR	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC240

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74HC240NSR.A	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC240
SN74HC240PWR	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC240
SN74HC240PWR.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC240
SN74HC240PWRG4	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC240
SNJ54HC240FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84074012A SNJ54HC 240FK
SNJ54HC240FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84074012A SNJ54HC 240FK
SNJ54HC240J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8407401RA SNJ54HC240J
SNJ54HC240J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8407401RA SNJ54HC240J
SNJ54HC240W	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8407401SA SNJ54HC240W
SNJ54HC240W.A	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8407401SA SNJ54HC240W

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

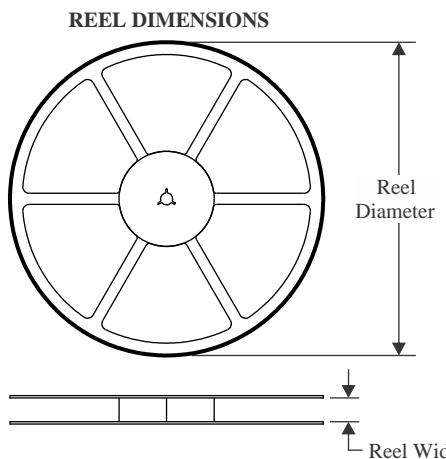
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HC240, SN74HC240 :

- Catalog : [SN74HC240](#)
- Military : [SN54HC240](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

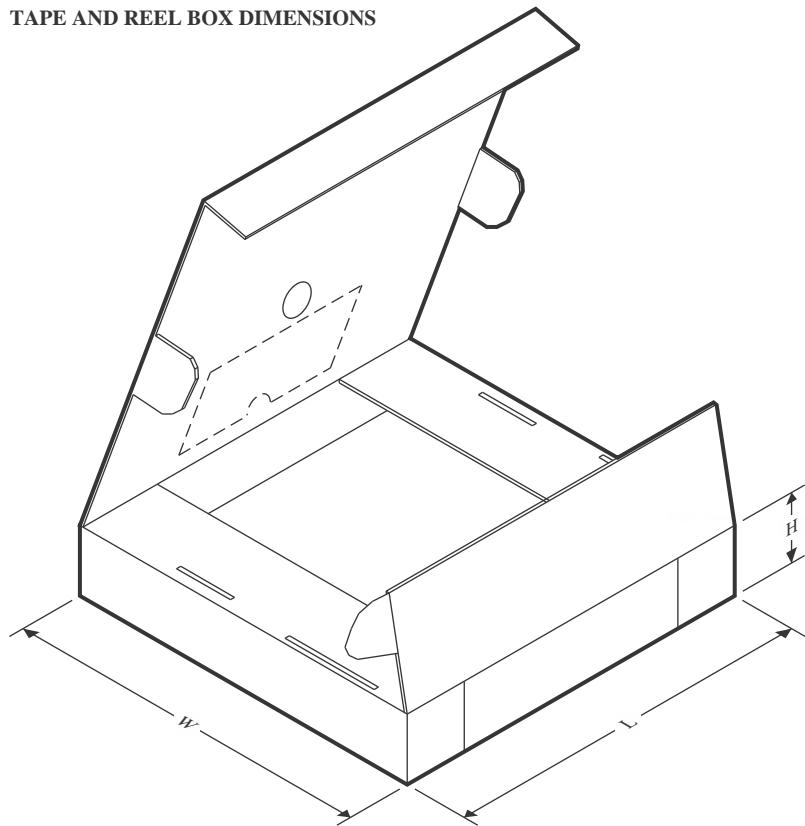
TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC240DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74HC240DGSR	VSSOP	DGS	20	5000	330.0	16.4	5.4	5.4	1.45	8.0	16.0	Q1
SN74HC240DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74HC240NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74HC240PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC240DBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74HC240DGSR	VSSOP	DGS	20	5000	353.0	353.0	32.0
SN74HC240DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74HC240NSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74HC240PWR	TSSOP	PW	20	2000	353.0	353.0	32.0

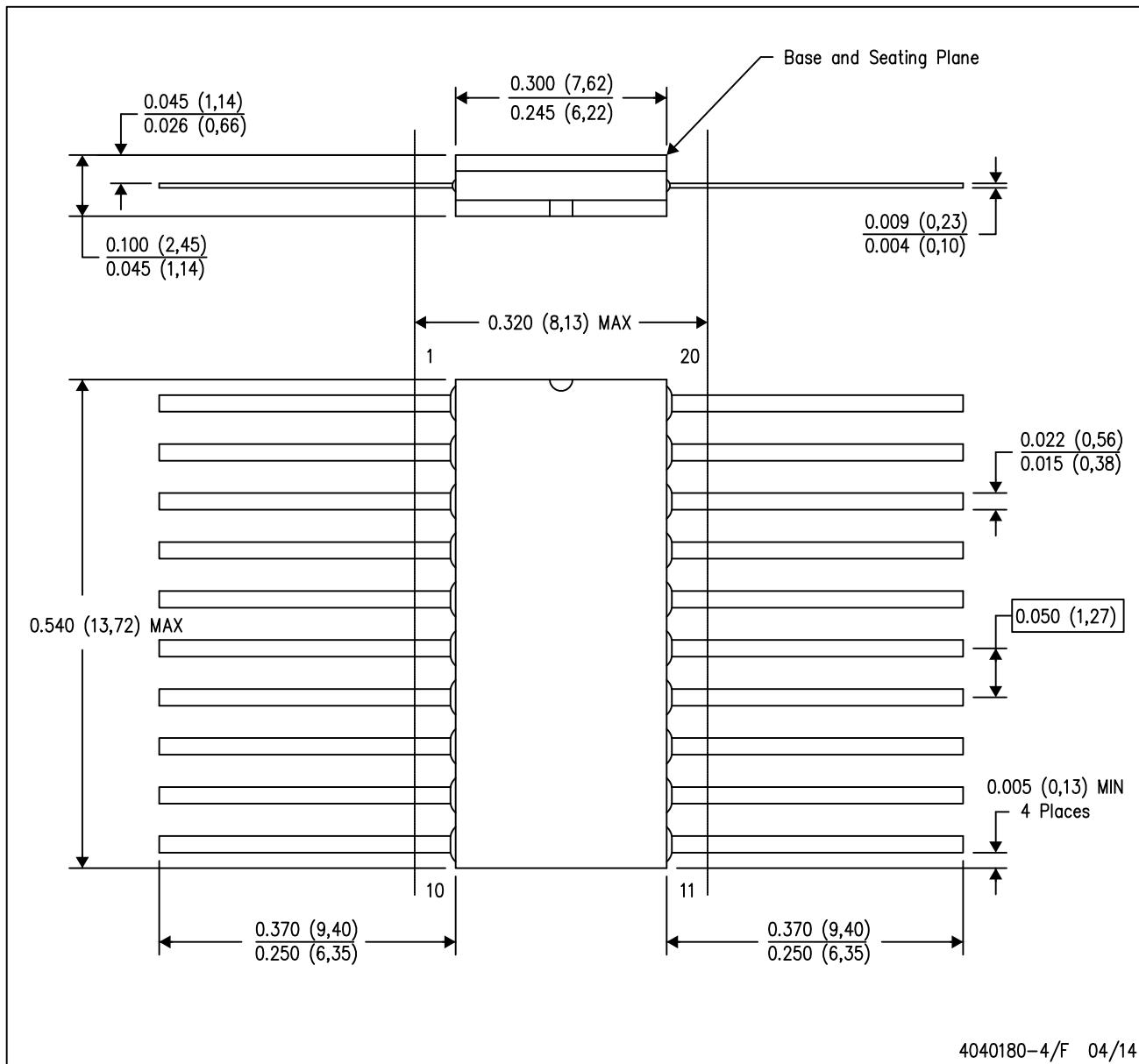
TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
84074012A	FK	LCCC	20	55	506.98	12.06	2030	NA
8407401SA	W	CFP	20	25	506.98	26.16	6220	NA
JM38510/65703B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/65703B2A.A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/65703B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74HC240N	N	PDIP	20	20	506	13.97	11230	4.32
SN74HC240N.A	N	PDIP	20	20	506	13.97	11230	4.32
SN74HC240NE4	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54HC240FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54HC240FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54HC240W	W	CFP	20	25	506.98	26.16	6220	NA
SNJ54HC240W.A	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

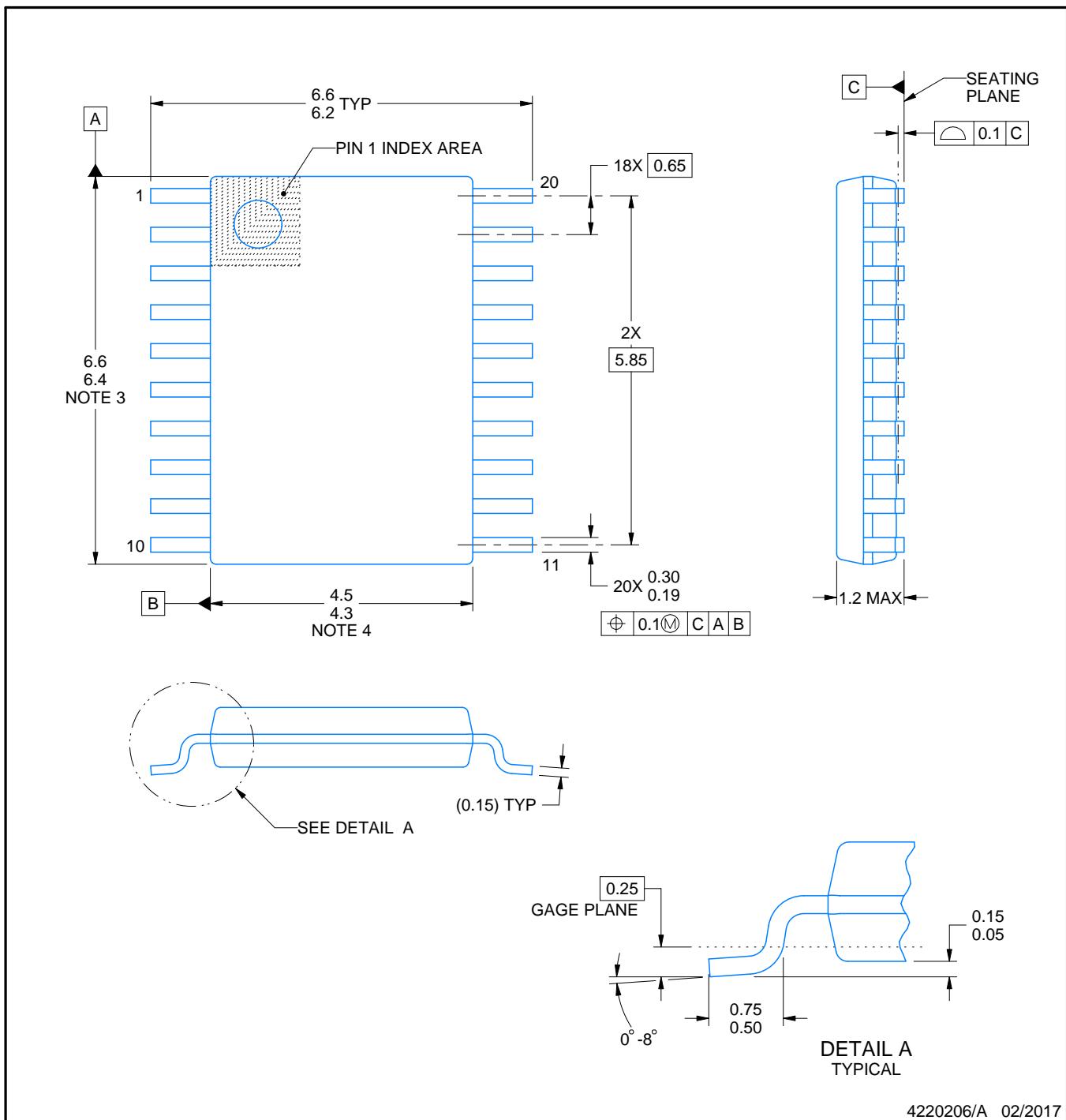
PACKAGE OUTLINE

PW0020A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

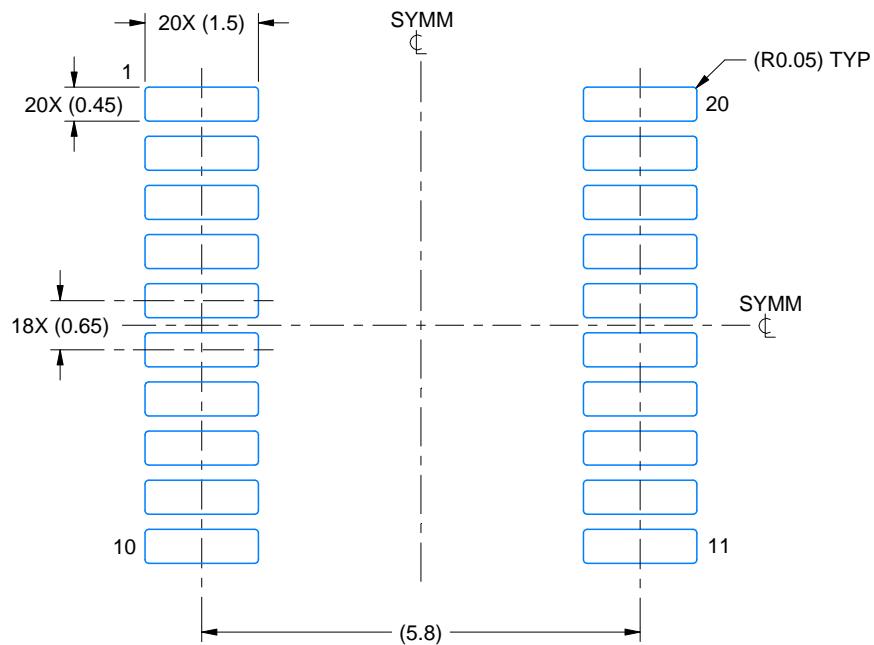
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

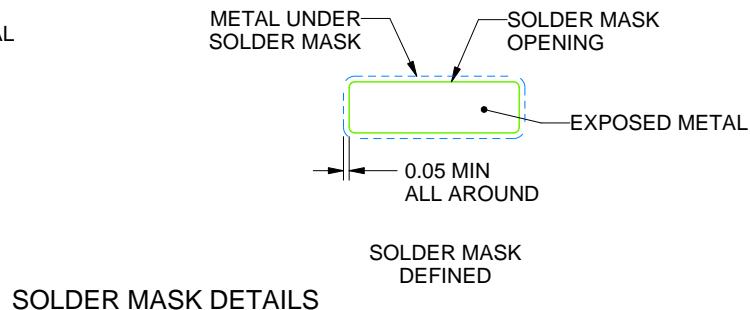
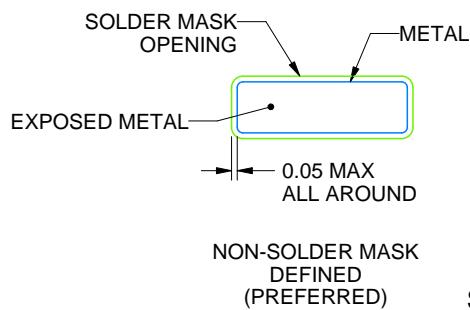
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

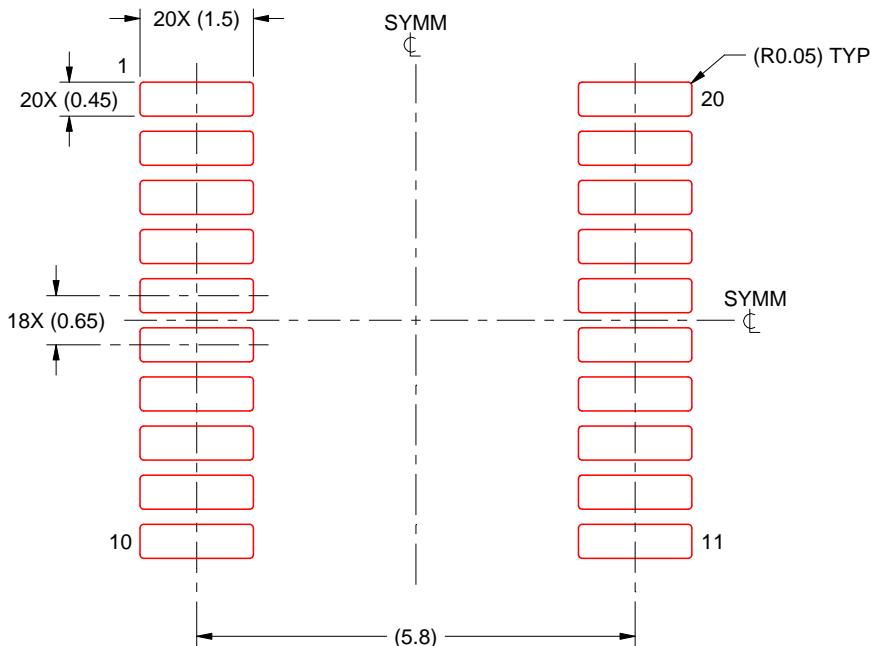
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

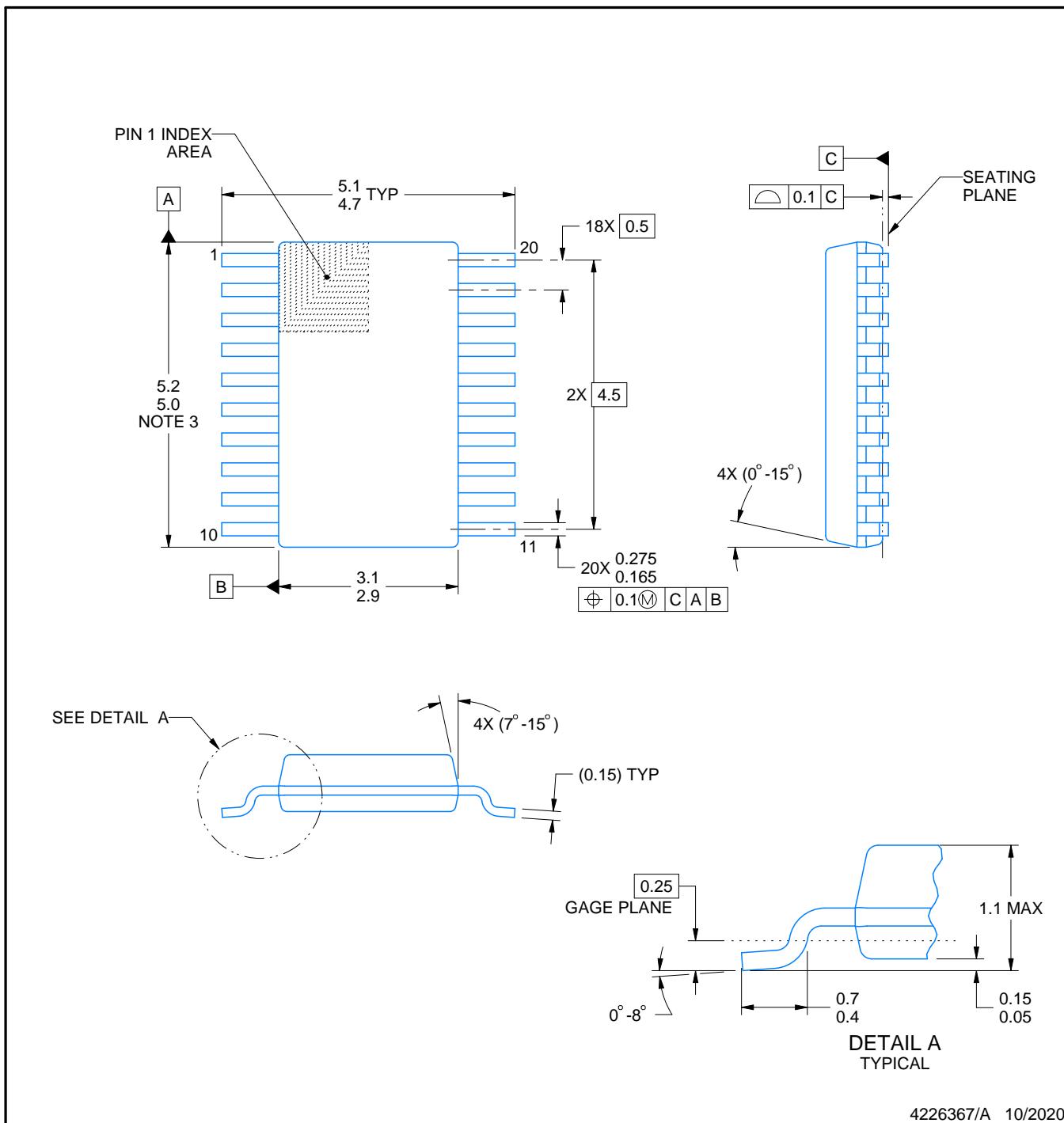
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



NOTES:

PowerPAD is a trademark of Texas Instruments.

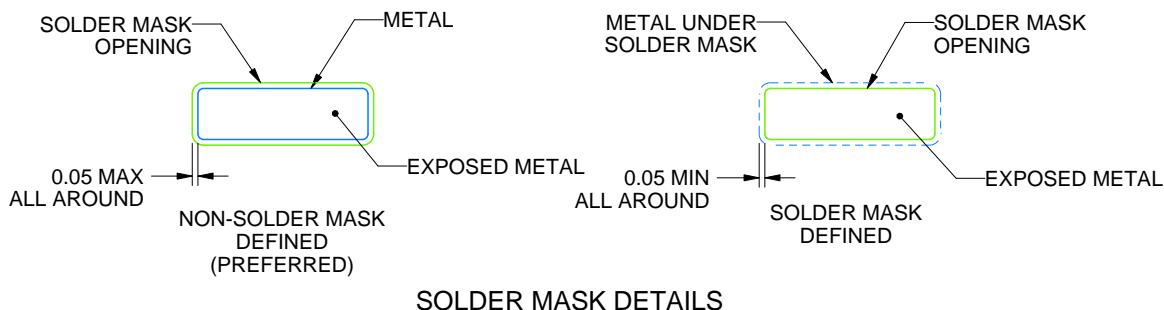
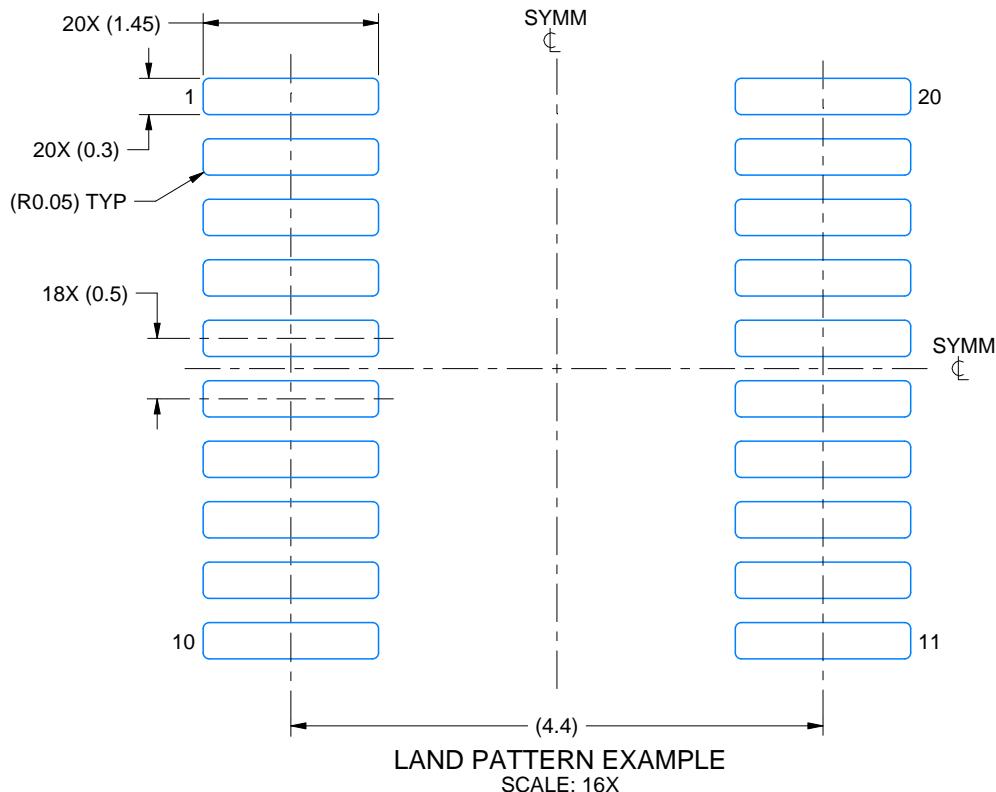
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of September 2020.
5. Features may differ or may not be present.

EXAMPLE BOARD LAYOUT

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4226367/A 10/2020

NOTES: (continued)

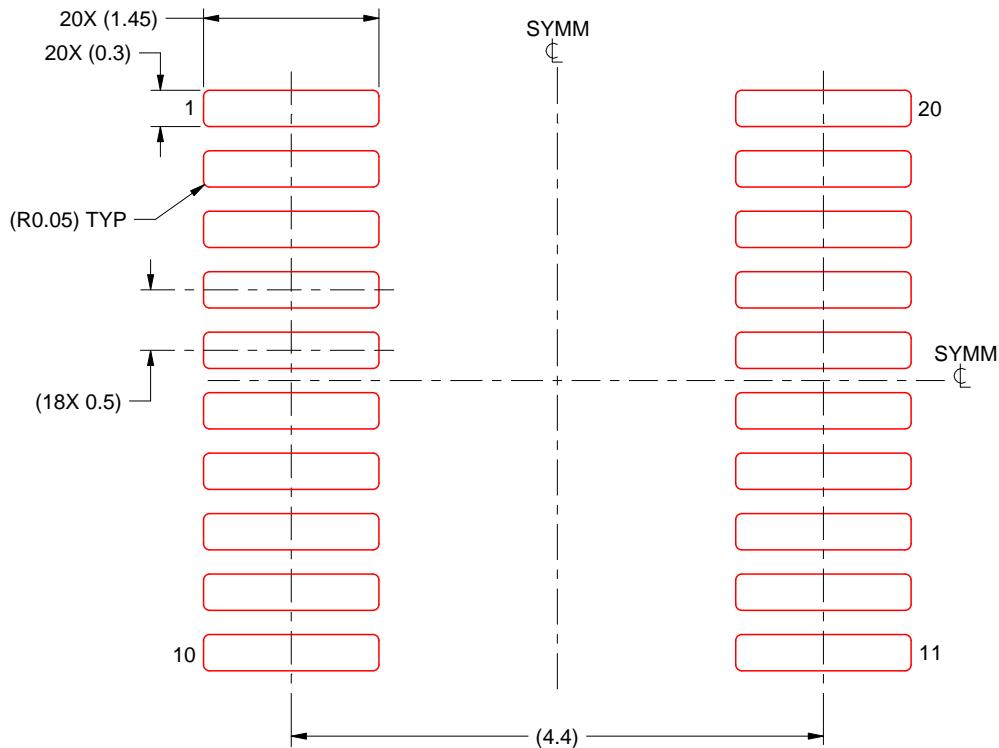
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 16X

4226367/A 10/2020

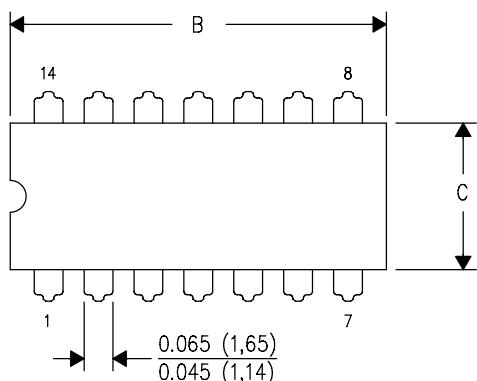
NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

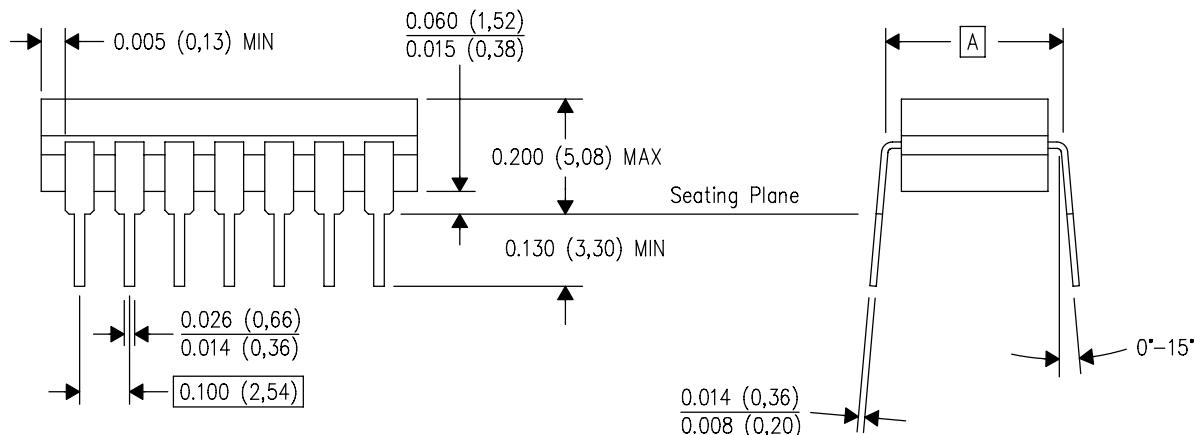
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

GENERIC PACKAGE VIEW

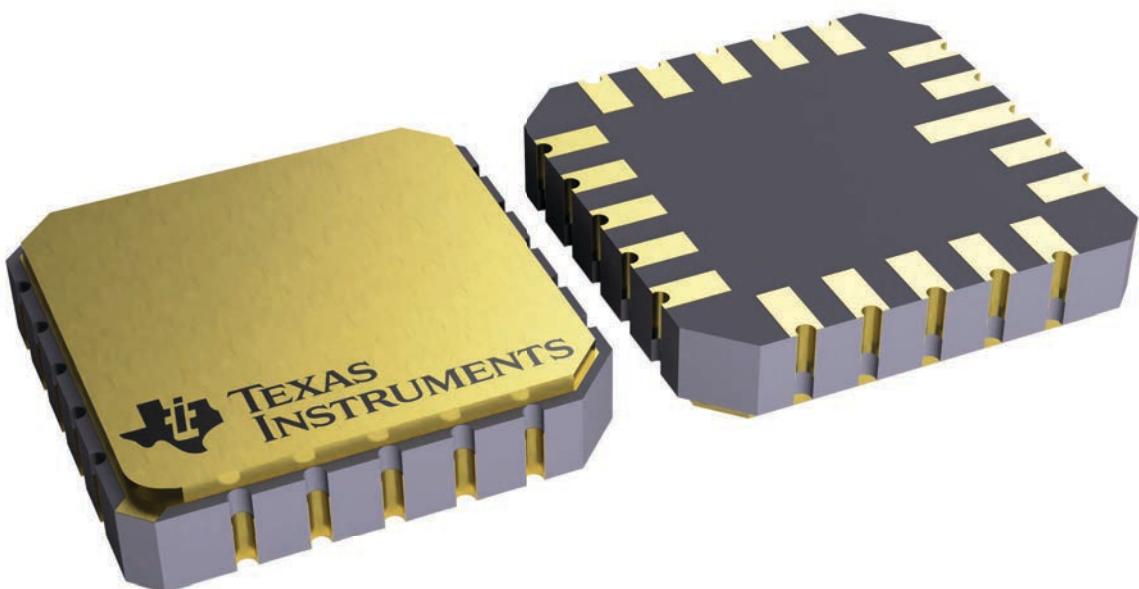
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

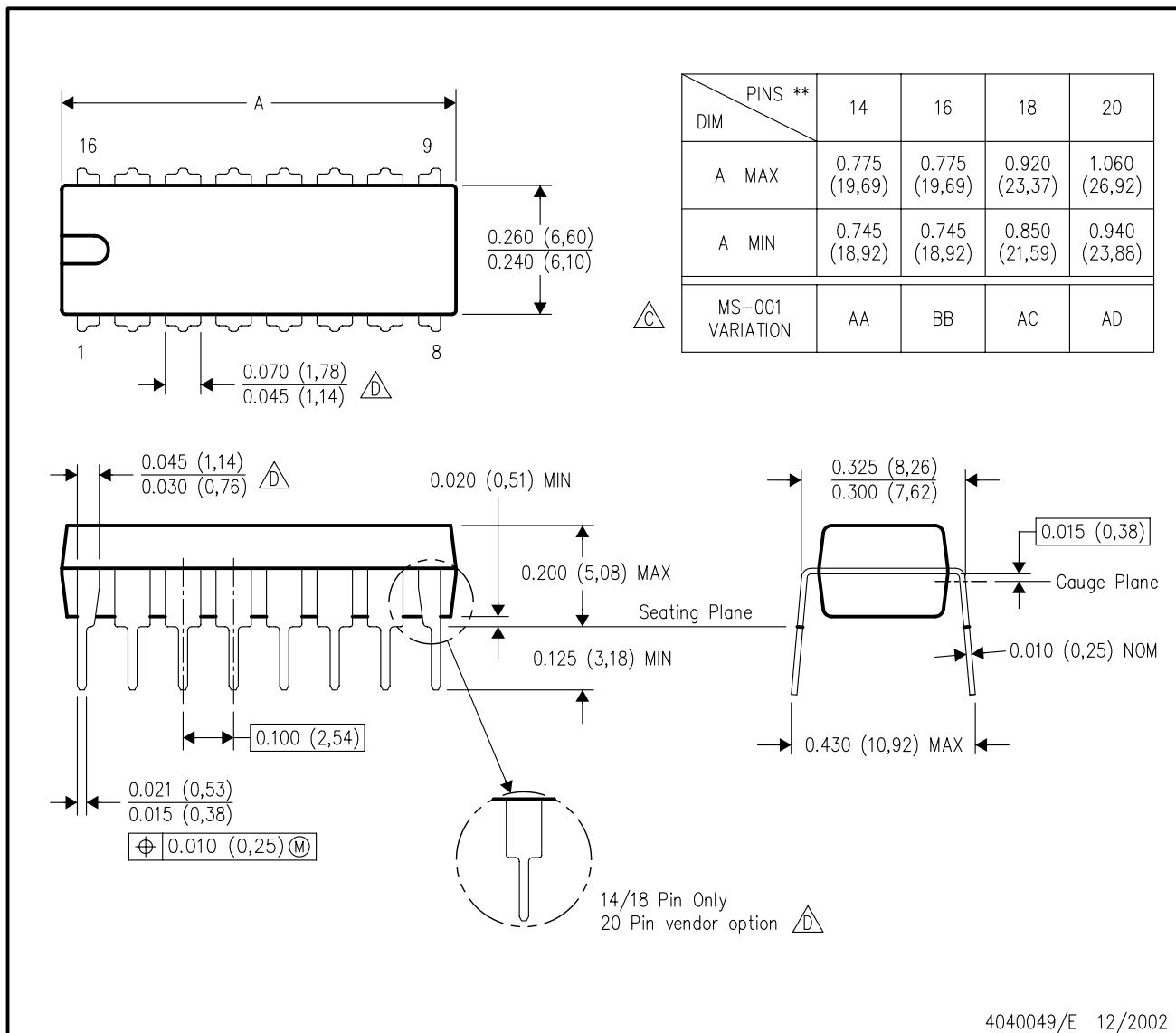


4229370VA\

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



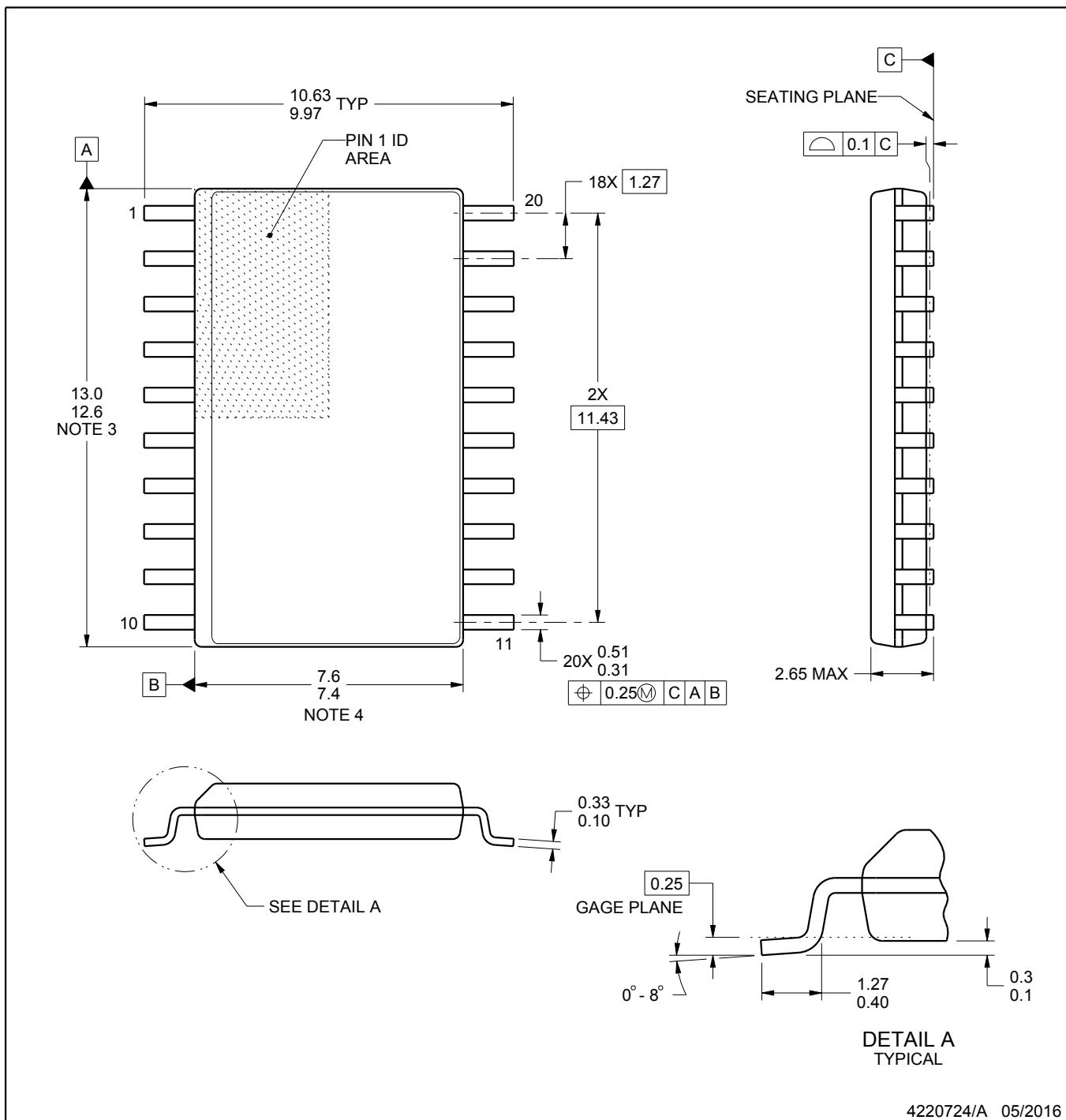
PACKAGE OUTLINE

DW0020A



SOIC - 2.65 mm max height

SOIC



NOTES:

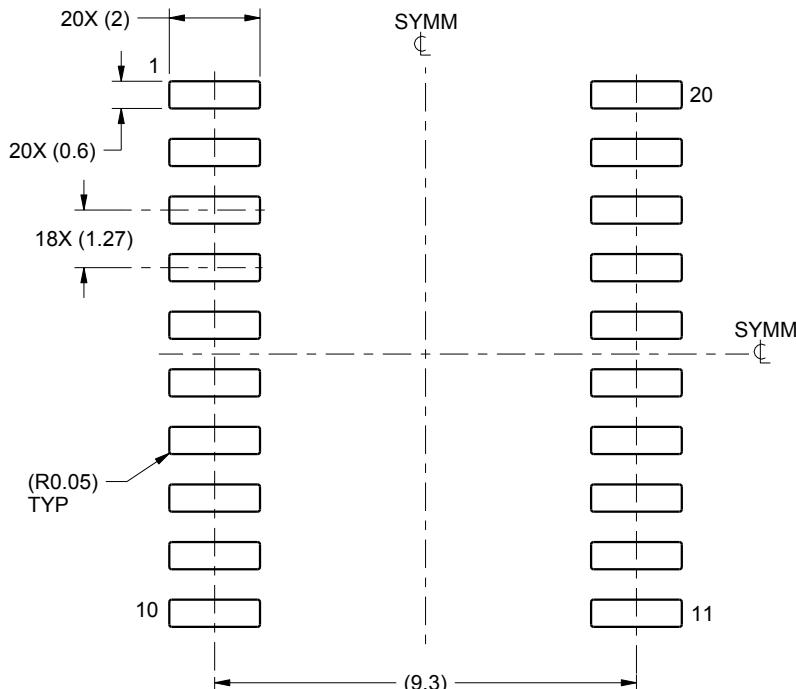
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

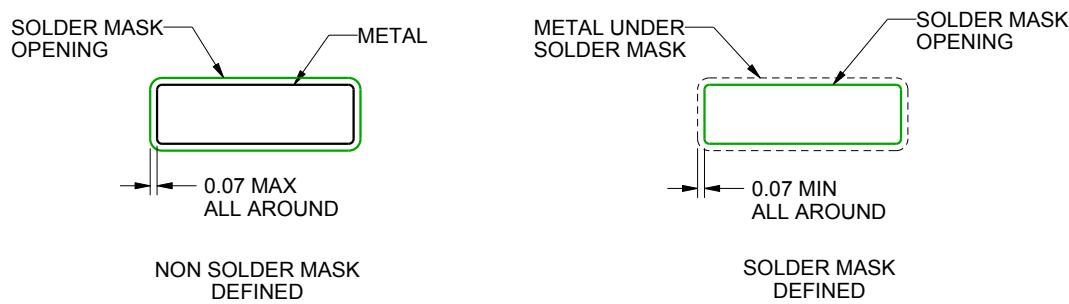
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

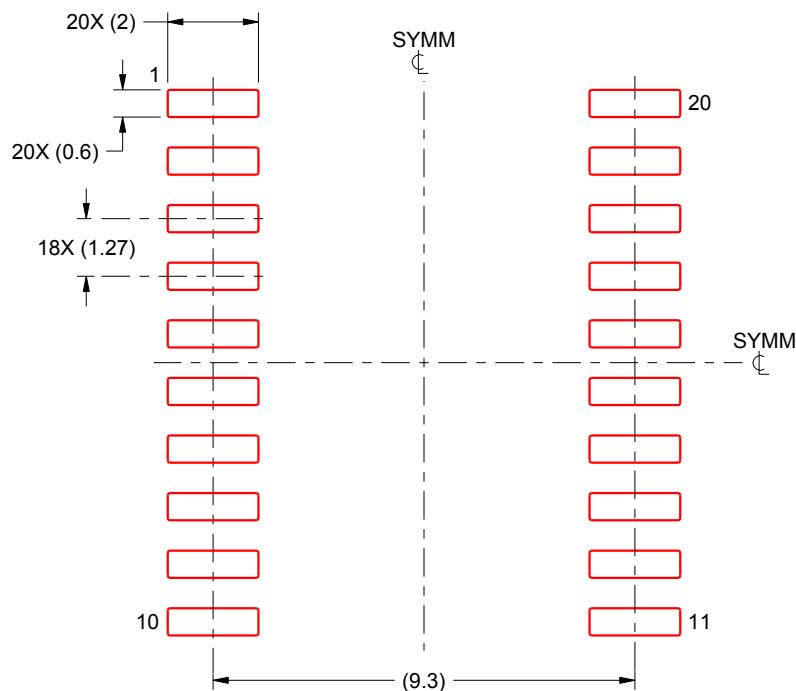
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

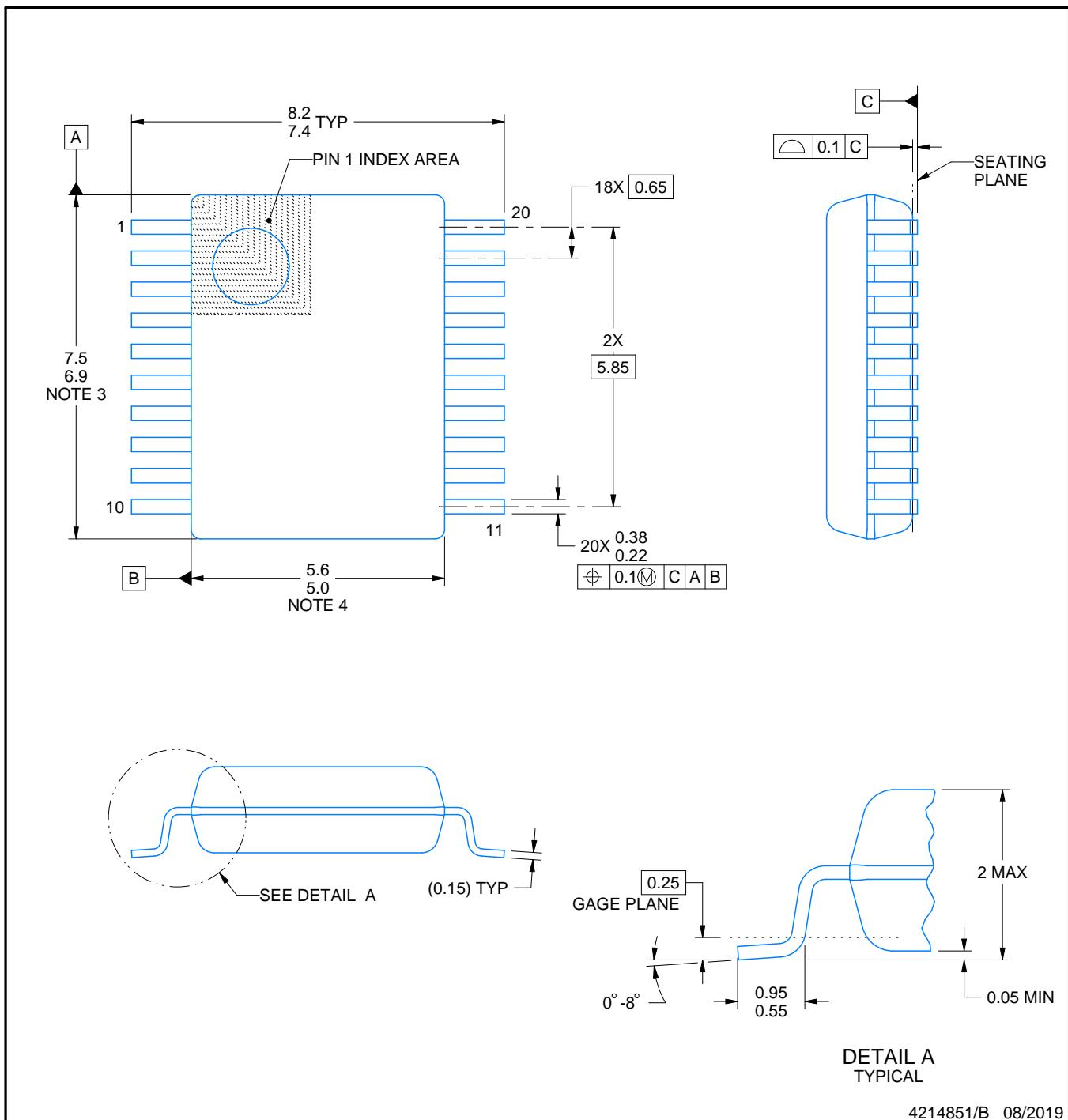
PACKAGE OUTLINE

DB0020A



SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

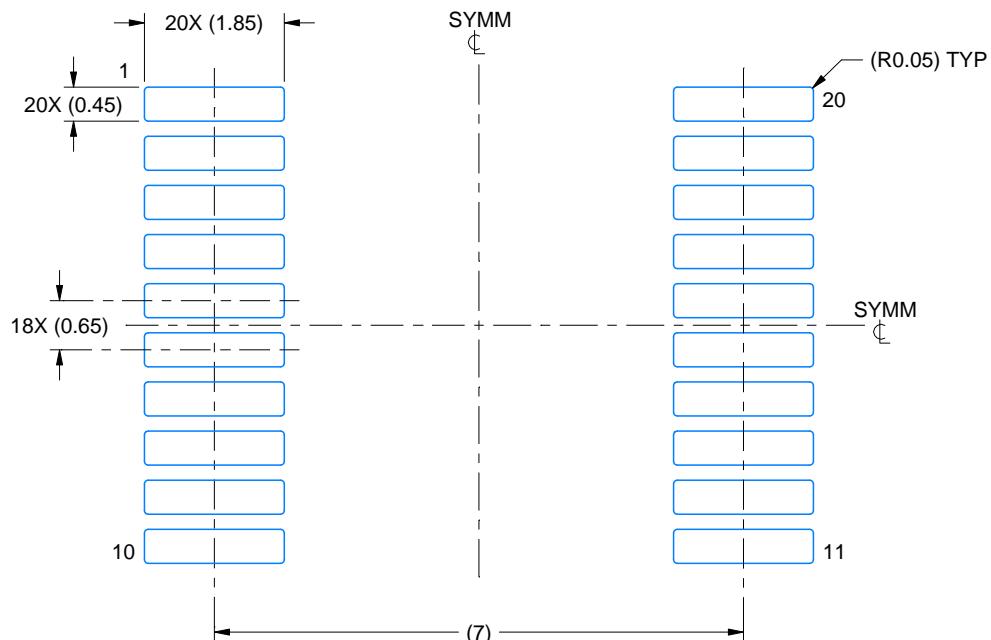
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

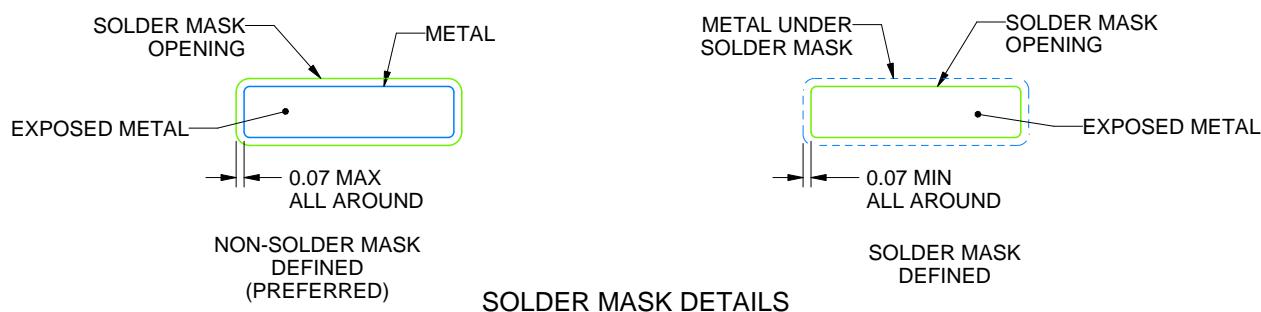
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

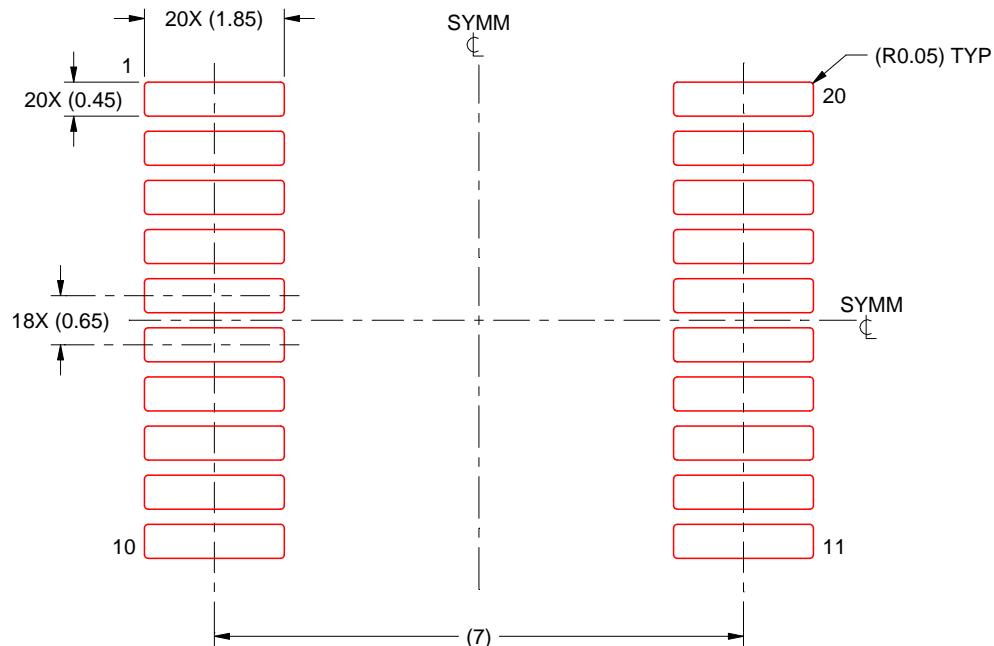
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

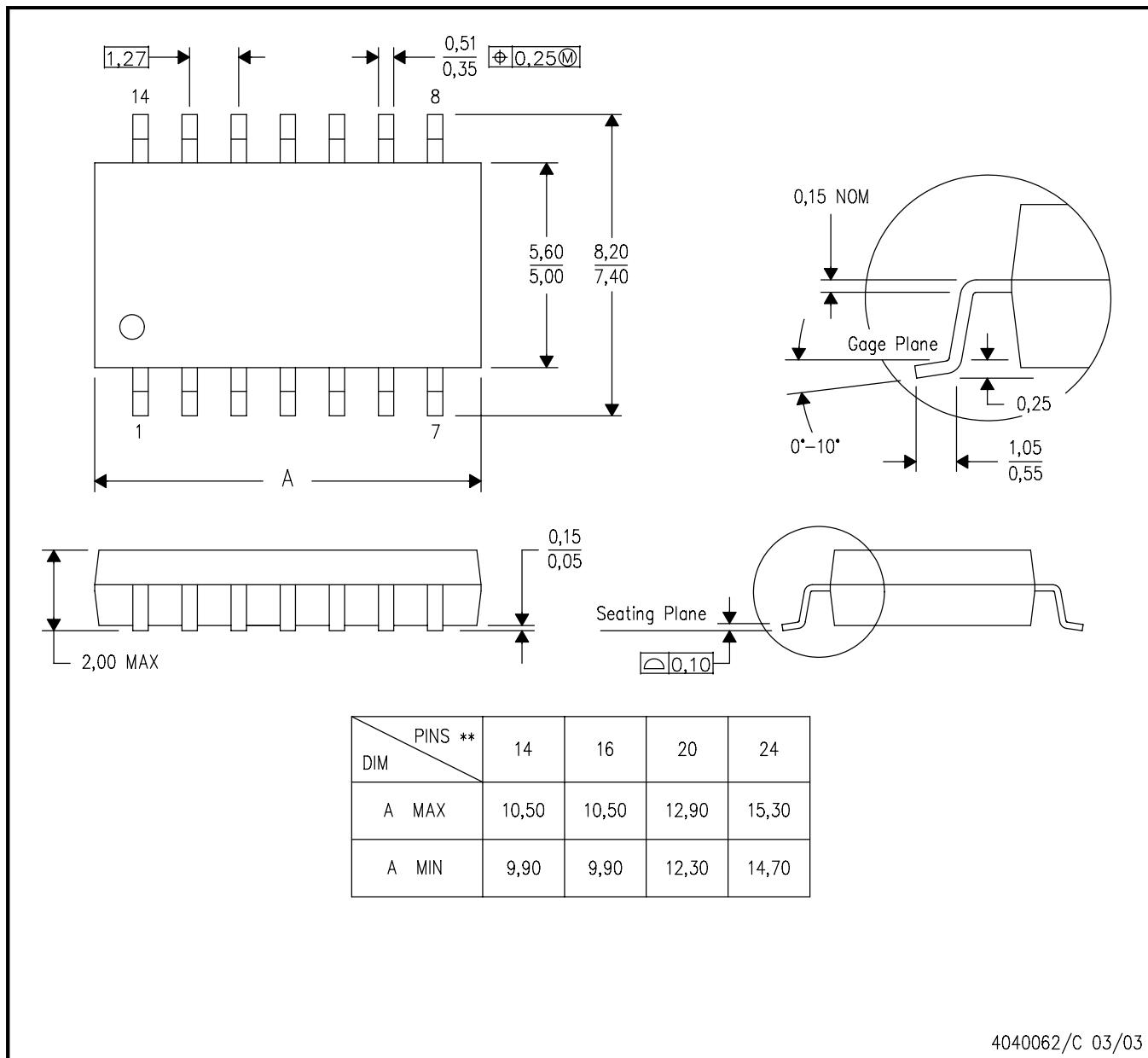
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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